

B1 [On page 1, line 2, insert - now US Patent 6,001,234, issued December 14, 1999 - -

[after "filed September 30, 1997".

3-20 After the foregoing amendment to page 1 has been made, please add the following
after "BooT.
after "September 30, 1997."

B2 - - This application is also a continuation-in-part of USSN 09/300,610, filed April 27, 1999, entitled "Electrode Semiconductor Workpiece Holder and Processing Methods", which is a continuation of USSN 08/680,057, filed July 15, 1996 and entitled "Electrode Semiconductor Workpiece Holder", now US Patent 5,980,706, issued November 9, 1999. pending 3/26/01

[IN THE CLAIMS:

1. (Amended) A contact assembly for supplying electrical power to a microelectronic workpiece during electrochemical processing of the microelectronic workpiece, the contact assembly comprising:

B3 an electrical contact for providing an electrically conductive connection between the contact assembly and the microelectronic workpiece; and

a yieldable sealing member having a rim portion proximate the electrical contact [for bearing] , the rim portion being adapted to bevel against the surface of the microelectronic workpiece as the workpiece and contact assembly are brought into engagement with one another, the rim portion forming [to form] a seal [thereagainst which] against the surface of the microelectronic workpiece to thereby inhibit [inhibits] to the entry of processing fluid

63 through a barrier which is defined between said yieldable sealing member and the surface of the microelectronic workpiece.

☐ 4. Canceled.

64 2/1. A contact assembly as claimed in claim [4], 2 wherein said electrical contact is recessed with respect to the rim portion of the yieldable sealing member, and said yieldable sealing member is adapted for deforming to enable the electrical contact to contact the surface of the microelectronic workpiece.

6. A contact assembly as claimed in claim 5 wherein the rim portion of the yieldable sealing member is adapted to splay outward when said yieldable sealing member deforms during contact with the surface of the microelectronic workpiece.

7. A contact assembly as claimed in claim 6 wherein when the yieldable sealing member splays outward the yieldable sealing member makes contact with the surface of the microelectronic workpiece along an internal side surface of the rim portion.

8. A contact assembly as claimed in claim 3 wherein the yieldable sealing member includes a bellows wall structure.

9. A contact assembly as claimed in claim 3 wherein the electrical contact includes a contact face for contacting the surface of the microelectronic workpiece.